

Serial No. 10/502,506

PU010288

In the Claims

1. (Original) An integrated circuit die for a flip chip comprising:
a die; and
a plurality of die bond pads situated on said die wherein said die bond pads are situated in rows with every other row having a bond pad spacing different than that of a bond pad spacing of an adjacent row.
2. (Original) The integrated circuit die of claim 1, wherein said plurality of die bond pads is positioned proximate an outside surface of said die.
3. (Original) The integrated circuit die of claim 1, wherein the bond pad spacing of every other row is twice the bond pad spacing of an adjacent row.
4. (Original) The integrated circuit die of claim 1, wherein said die bond pads situated in rows define row-pairs, a first row of a row pair having a first bond pad spacing defining a first pitch, and a second row of the row pair having a second bond pad spacing defining a second pitch that is different than that of said first pitch.
5. (Original) The integrated circuit die of claim 4, wherein said first row of the row pair is situated proximate an outside edge of said die.
6. (Original) The integrated circuit die of claim 1, wherein each die bond pad is circular.
7. (Original) The integrated circuit die of claim 6, wherein each circular bond pad has a diameter of approximately 5 mils.
8. (Original) An integrated circuit die for a flip chip comprising:
die means; and

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a plurality of die bond pads situated on said die means wherein said die bond pads are situated in rows with every other row having a bond pad spacing different than that of a bond pad spacing of an adjacent row.

9. (Original) The integrated circuit die of claim 8, wherein said rows of said plurality of die bond pads are positioned proximate an outside surface of said die means.

10. (Original) The integrated circuit die of claim 9, wherein the bond pad spacing of every other row is twice the bond pad spacing of an adjacent row.

11. (Original) The integrated circuit die of claim 9, wherein said die bond pads are situated in rows defining row pairs, a first row of a row pair having a first bond pad spacing defining a first pitch, and a second row of the row pair having a second bond pad spacing defining a second pitch that is different than that of said first pitch.

12. (Original) The integrated circuit die of claim 11, wherein said first row of the row pair is situated proximate an outside edge of said die means.

13. (Original) The integrated circuit die of claim 8, wherein each die bond pad is circular.

14. (Original) The integrated circuit die of claim 13, wherein each circular bond pad has a diameter of approximately 5 mils.

15. (Original) A method of fabricating an integrated circuit die for a flip chip comprising the steps of:

providing an integrated circuit die; and

providing a plurality of die bond pads situated on said integrated circuit die wherein said plurality of die bond pads are situated in rows with every other row having a bond pad spacing different than that of a bond pad spacing of an adjacent row.

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16. (Original) The integrated circuit die of claim 15, wherein said step of providing a plurality of die bond pads comprises positioning the rows of die bond pads proximate an outside surface of said die.

17. (Original) The integrated circuit die of claim 16, wherein the step of providing rows of bond pads beginning proximate an outside surface of said integrated circuit die includes the step of providing rows of bond pads with every other row having a bond pad spacing twice that of a bond pad spacing of an adjacent row.

18. (Original) The method of claim 16, wherein the step of providing rows of bond pads with every other row having a bond pad spacing different than that of a bond pad spacing of an adjacent row includes the step of situating the bond pads in rows defining row pairs, a first row of a row pair having a first bond pad spacing defining a first pitch, and a second row of the row pair having a second bond pad spacing defining a second pitch that is different than that of said first pitch.

19. (Original) The method of claim 18, wherein said first row of the row pair is situated proximate an outside edge of said die.

20. (Original) The method of claim 15, wherein each die bond pad is circular.

21. (Original) The method of claim 20, wherein each circular die bond pad has a diameter of approximately 5 mils.